

#### **Power Light Source**

Introduction :

THCA-DLx is one the highest flux LEDs in the world. THCA-DLx LED has offered extended solid-state lighting design possibilities.Due to the special design of chip and package, the THCA-DLX is designed by particular package for high power LED.



Blue 
 Cyan 
 Green



Amber 

Red 

Crimson

### Feature :

- Long operating life
- Energy efficiency
- Low thermal resistance
- Compact design
- Instant light
- Fully dimmable
- Superior ESD protection
- ROHS compatibility

#### **Typical Applications:**

- Reading lights
- Portable light
- Orientation
- Entertainment
- Garden
- Security light
- Ceiling light
- Architectural lighting
- General lighting
- Jewel display illumination



## Package Dimensions







Dimension

### Circuit Diagram



Notes :

- 1. All dimensions are in millimeters
- 2. Tolerance is ±0.25mm



# Absolute Maximum Ratings

Parameter	Rating
DC Forward Current (mA)	700
Max Pulsed Forward Current[1] IF(Max Pulsed)	900
LED Junction Temperature (°C)	120
Operating Board Temperature ( $^{\circ}C$ )	-30~90
Storage Temperature (°C)	-40~110
Soldering Temperature	Manual 240°C (max) 5 seconds
Reverse Voltage (V <sub>R</sub> )	Not designed to be driven in reverse bias

Notes :

[1]. less than 1/10 duty cycle@1KHz

Calar	Domir	nant Waveleng	Viewing Angle	Radiation			
Color	Min.	Тур.	Max.	(degrees) 2θ1/2	Pattern		
Red	613.5 nm	623 nm	631 nm	125			
Amber	587 nm	592 nm	597 nm	125			
Green	515 nm	525 nm	535 nm	125			
Cyan	495nm	505nm	515nm	125	Lombortion		
Blue	455 nm	465 nm	475 nm	125	Lambertian		
Royal Blue	450nm	455nm	460nm	125			
Crimson (1)	650nm	660nm	670nm	125			
Cherry Red (1)	720nm	730nm	740nm	125			

## Optical Characteristics@700mA, TJ= 25°C

• Maintains a tolerance of ± 1nm for dominant wavelength measurements.

(1)Crimson, Cherry Red product is binned by peak wavelength rather than dominant wavelength.



Radiation	Color	Part Number Lumino		us Flux ΦV(lm)	
Pattern	COIOI	Emitter	Minimum	Typical	
	Red	THCA-DLR	90lm	120lm	
	Amber	THCA-DLA	90lm	130lm	
	Green	THCA-DLG	140lm	230lm	
Lambertian	Cyan	THCA-DLC	115lm	135lm	
Lampertian	Blue	THCA-DLB	40lm	50lm	
	Royal Blue	THCA-DLY	880mW	1100mW	
	Crimson	THCA-DLP	750mW	850mW	
	Cherry Red(1)	THCA-DLI	600mW	730mW	

## Flux Characteristics@700mA, TJ= 25°CElectrical

- Maintains a tolerance of  $\pm 7\%$  on flux and power measurements.
- Please do not drive at rated current more than 1 second without proper heat sink.

### Electrical Characteristics@700mA. TJ= 25°Coptical

Calar	Fo	ward Voltage V <sub>F</sub>	(V)	Thermal Resistance
Color	Min.	Тур.	Max.	Junction to Slug (°C/W)
Red	1.8	2.5	3.2	8
Amber	1.8	2.5	3.2	8
Green	3.0	3.5	4.0	8
Cyan	3.0	3.5	4.0	8
Blue	3.0	3.5	4.0	8
Royal Blue	3.0	3.5	4.0	8
Crimson	1.85	2.5	2.8	8
Cherry Red	2.0	2.35	2.7	8

Maintains a tolerance of  $\pm 0.1V$  for Voltage measurements. •



## **RELIABILITY ITEMS and SPECTIONS**

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life (RTOL)	25°C, I <sub>F</sub> = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Operating Life (WHTOL)	85°C/60%RH, I <sub>F</sub> = max DC (Note 1)	1000 hours	Note 2
Wet High Temperature Storage Life (WHTSL)	85°C/85%RH, non-operating	1000 hours	Note 2
High Temperature Storage Life (HTSL)	110°C, non-operating	1000 hours	Note 2
Low Temperature Storage Life (LTSL)	-40°C, non-operating	1000 hours	Note 2
Non-operating Temperature Cycle (TMCL)	-40°C to 120°C, 30 min. dwell, <5 min. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse, 5 shocks each 6 axis		Note 3
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration Frequency	10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Solderability	Steam age for 16 hrs., then solder dip at 260°C for 5 sec.		Solder coverage on lead

#### Notes:

- 1. Depending on the maximum derating curve.
- 2. Criteria for judging failure

		Criteria for	Judgement
ltem	Test Condition	Min.	Max.
Forward Voltage (V <sub>F</sub> )	I <sub>F</sub> = max DC		Initial Level x 1.1
Luminous Flux or	I <sub>F</sub> = max DC	Initial Level x 0.7	
Reverse Current (I <sub>R</sub> )	$V_R = 5V$		50 µA

\* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.



## Color Spectrum, TJ = 25°C



## **Typical Spatial Radiation Pattern**





## Light Output Characteristics

Relative Light Output vs. Junction Temperature at 350mA





Forward Current Characteristics, TJ = 25°C



Forward Voltage vs. Forward Current

Forward Current vs. Normalized Relative Luminous Flux





## RHMoisture Sensitivity Level -JEDEC Leve 3

	Floor Life		Soak Requirements			
Level	FIOO	r Life	Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
3	168 hours	≦30/60%	192+5/-0	30/60	40+1/-0	60/60

• The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

• Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

	Floor Life		Soak Requirements			
Level			Stand	dard	Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
1	Unlimited	≤30°C / 85% RH	168 +5/-0	85°C / 85% RH	NA	NA
2	1 year	≤30°C / 60% RH	168 +5/-0	85°C / 60% RH	NA	NA
2a	4 weeks	≤30°C / 60% RH	696 +5/-0	30°C / 60% RH	120 +1/-0	60°C / 60% RH
3	168 hours	≤30°C / 60% RH	192 +5/-0	30°C / 60% RH	40 +1/-0	60°C / 60% RH
4	72 hours	≤30°C / 60% RH	96 +2/-0	30°C / 60% RH	20 +0.5/-0	60°C / 60% RH
5	48 hours	≤30°C / 60% RH	72 +2/-0	30°C / 60% RH	15 +0.5/-0	60°C / 60% RH
5a	24 hours	≤30°C / 60% RH	48 +2/-0	30°C / 60% RH	10 +0.5/-0	60°C / 60% RH
6	Time on Label (TOL)	≤30°C / 60% RH	Time on Label (TOL)	30°C / 60% RH	NA	NA



## **Recommended Solder Pad Design**



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.



### **Reflow Soldering Temperature Profile**



Profile Feature	Typical parameters
Average Ramp-Up Rate (Ts <sub>max</sub> to Tp)	3 °C/second max.
Preheat Temperature Min (Ts <sub>min</sub> )	150 °C
Preheat Temperature Max (Ts <sub>max</sub> )	200 ℃
Time (Ts <sub>min</sub> to Ts <sub>max</sub> )	60-180 seconds
Time maintained above Temperature (TL)	217 ℃
Time maintained above Time (TL)	60-150 seconds
Peak/Classification Temperature (Tp)	240 ℃
Time within 5 °C of Actual Peak Temperature (Tp)	5 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
  double-head soldering iron should be used. It should be confirmed beforehand whether the
  characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



## **Tape and Reel Packaging Specifications**

• Carrier Tape Dimensions



Notes:

- 1. Drawing not to scale.
- 2. All dimensions are in millimeters.
- 3. Unless otherwise indicated, tolerances are  $\pm$  0.10mm.



Reel Dimensions



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 1000 pieces per reel.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters



### Notice

- In order to avoid absorption of moisture, it is recommended that the products are stored in the dry box (or desiccators) with a desiccants. Alternatively the following environment is recommended: Storage temperature : 5°C~30°C Humidity:60% HR max.
- If the storage conditions are of high humidity the product should be dried before use. Recommended drying conditions: 12 hours at 60°C±5°C.
- Any mechanical force or any excess vibration should be avoid during the cooling process after soldering.
- Reflow rapidly cooling should be avoided.
- Components should not be mounted on distorted Printed Circuit Boards.
- Devices should not contact with any types of fluid, such as water , oil , organic solvents.... etc.
- The maximum ambient temperature should be taken into consideration when determining the operating current.
- Devices should be soldered within 7 days after opening the moisture-proof packing.
- Repack unused product in anti-moisture packing, fold to close any opening and store in a dry place.
- The appearance and specifications of devices may be modified for improvement without notice.
- ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handing the LEDs. All devices, equipment and machinery should be properly grounded.
- This product must be driven by constant power supplier.

## Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 0.3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)

